BGA Heat Sink (High Aspect Ratio Ext.) Standard Pin Fin



ATS Part#:

Description:

ATS021021006-PF010

21.00 x 21.00 x 6.40 mm BGA Heat Sink (High Aspect Ratio Ext.) Standard Pin Fin

Heat Sink Type: Standard Pin Fin Heat Sink Attachment: Equivalent Part Number: N/A

N/A

*Image above is for illustration purpose only.

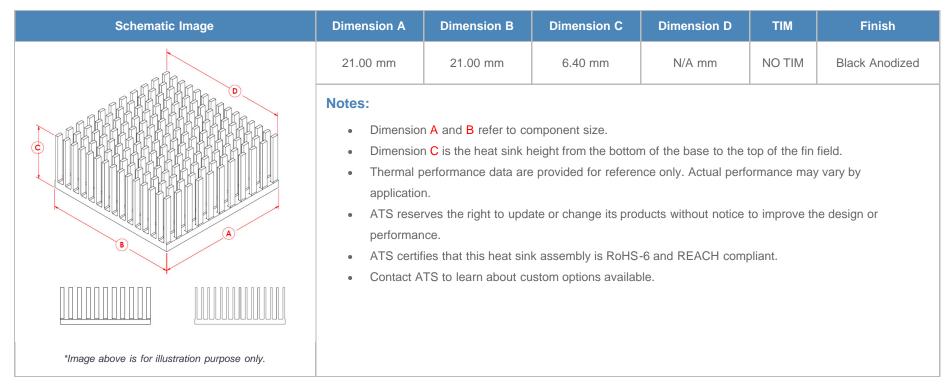
Features & Benefits

- Excellent balance of low cost and high performance in an aluminum heat sink. .
- Designed for semiconductor devices with omni-directional airflow requirements. .
- 6x6 pin array
- Available with a variety of thermal adhesive tape options. Contact sales@qats.com for product configurations.

Thermal Performance

		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	24 °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W	N/A °C/W
	Ducted Flow	0	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail



For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

